



Model Type : LS-SF67(8)1 top view Series

Power Top View LED

Model No. : LS-SF67(8)1DLG74

■ Features :

- PLCC-2 package and high flux output
- Compatible reflow solder and wave solder process.
- Compatible with automatic placement equipment.
- Available on tape and reel(8mm tape)

■ Applications :

- Automotive: interior and exterior lighting
- Indicators
- Flat backlight for LCD's switches and symbols
- General use

Dice Material	Light Color	Lens Color
InGaN	Green	Water Clear

Absolute Maximum Ratings

(Ta=25°C)

Item	Symbol	Maximum	Unit
Power Dissipation	P _D	100	mW
Continuous Forward Current	I _F	30	mA
Peak Forward Current (1/10 Duty Cycle 0.1ms Pulse Width)	I _{FP}	100	mA
Reverse Voltage	V _R	5	V
Derating Linear From 25°C		0.4	mA/°C
Operating Temperature Range	Topr	-40 to +85	°C
Storage Temperature Range	Tstg	-40 to +100	°C
Lead Soldering Temp.(1.6mm from body) for 5seconds		260	°C
Electrostatic discharge (ESD)		300	V

Electrical / Optical Characteristics

(Ta=25°C)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V _F	IF=20mA		3.30	4.20	V
Reverse Current	I _R	VR=5V			10	uA
Peak Emission Wavelength	λ _p	IF=20mA		523		nm
Dominant Wavelength	λ _D	IF=20mA		525		nm
Viewing Angle	2 θ 1/2	IF=20mA		120		Deg
Luminous Intensity	I _v	IF=20mA	360	570		mcd

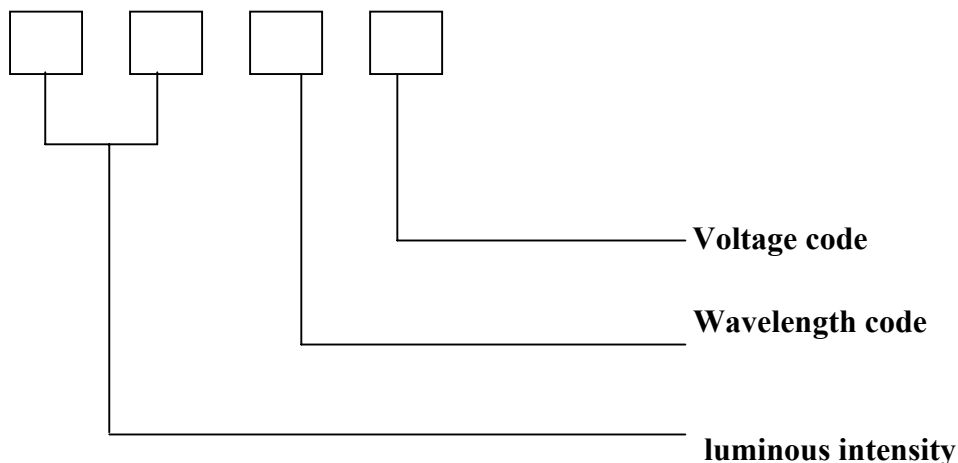
ISSUE	DIMENSION NO :	VERSION :	DATE :
		A	2007/07/31
	APPROVAL :	CHECK :	EDIT :



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◆ Packing coding principle

Notice: Bin code: luminous intensity / wavelength / voltage.



◆ The Luminous Intensity Grade of Blue Chip-LED Products

● Test Condition : @ 20mA

Range,mcd	Bin code
360/450	N2
450/570	P1
570/720	P2
720/900	Q1

◆ Dominant Wavelength Grade of Blue Chip-LED Products

● I type @ 20mA

BIN	Range	BIN	Range
3	516.5~519	7	526.5~529
4	519~521.5	8	529~531.5
5	521.5~524	9	531.5~534
6	524~526.5	A	534~536.5

◆ Forward Voltage Grade of Blue Chip-LED Products

● I type @ 20mA

BIN	Range	BIN	Range
2	2.9/3.0	5	3.2~3.3
3	3.0~3.1	6	3.3~3.4
4	3.1~3.2	7	3.4~3.5



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◆ **Descriptions :**

- The Chip-LED Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature application, etc.

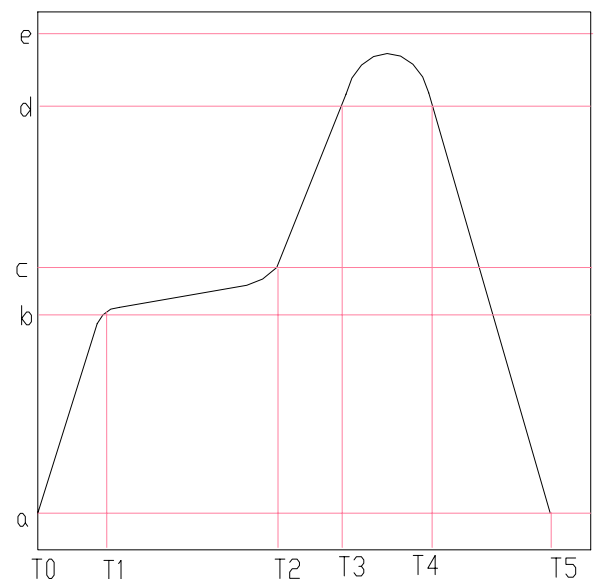
◆ **Reliability Test Items And Conditions :**

NO.	Item	Test Conditions	Test Hours / Cycle	Sample Q'ty	Ac / Re
1	Solder Heat	TEMP : 260°C±5°C	5 sec	36 pcs	0 / 1
2	Temperature Cycle	H : +100°C 30min. ∫ 5min. L : -40°C 30min.	50 cycle	36 pcs	0 / 1
3	Thermal Shock	H : +100°C 5min. ∫ 10sec L : -40°C 5min.	50 cycle	36 pcs	0 / 1
4	High Temperature Storage	TEMP : 100°C	1000 hrs	36 pcs	0 / 1
5	Low Temperature Storage	TEMP : -40°C	1000 hrs	36 pcs	0 / 1
6	DC Operating Life	I _F = 20mA	1000 hrs	36 pcs	0 / 1
7	High Temperature / High Humidity	85°C / 90~95%R.H.	1000 hrs	36 pcs	0 / 1

◆ **Reflow Temp. / Time : :**

Please refer to the following figure :

Temp.(°C)		Time(Sec)	
a	25	T0~T1	Max. 3°C/sec
b	150	T1~T2	90~130 sec
c	200	T2~T3	Max. 3°C/sec
d	220	T3~T4	Max. 30~50 sec
e	250		
		T4~T5	Max. -3°C/sec
Blot Speed		70~90 cm/min	

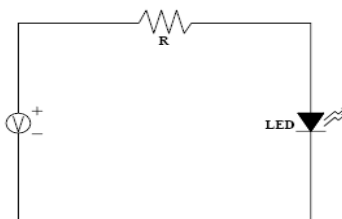


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◆ Precautions For Use :

- Over – current – proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)



- Storage

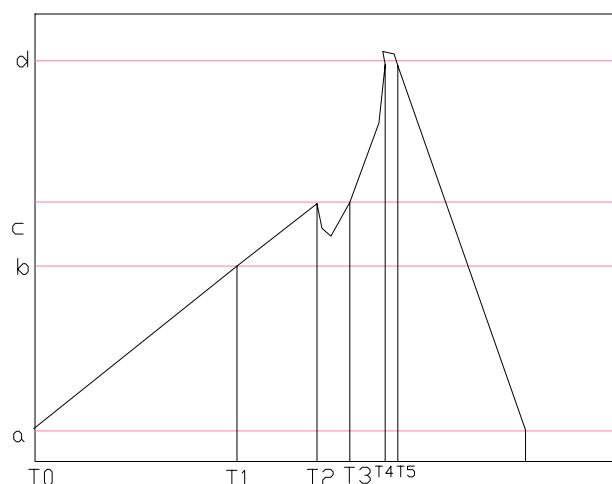
1. The operation of temperature and R.H. are : $5^{\circ}\text{C} \sim 30^{\circ}\text{C}$, R.H.60% Max..
2. Once the package is opened, the products should be used within 72 hrs. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1 year (from production date) .
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $80^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 24hrs.

◆ Soldering Iron :

- Temperature at tip of iron : 300°C Max. (25W Max.)
- Soldering time : $5 \pm 1\text{sec}$.

◆ Wave Soldering Temp. / Time :

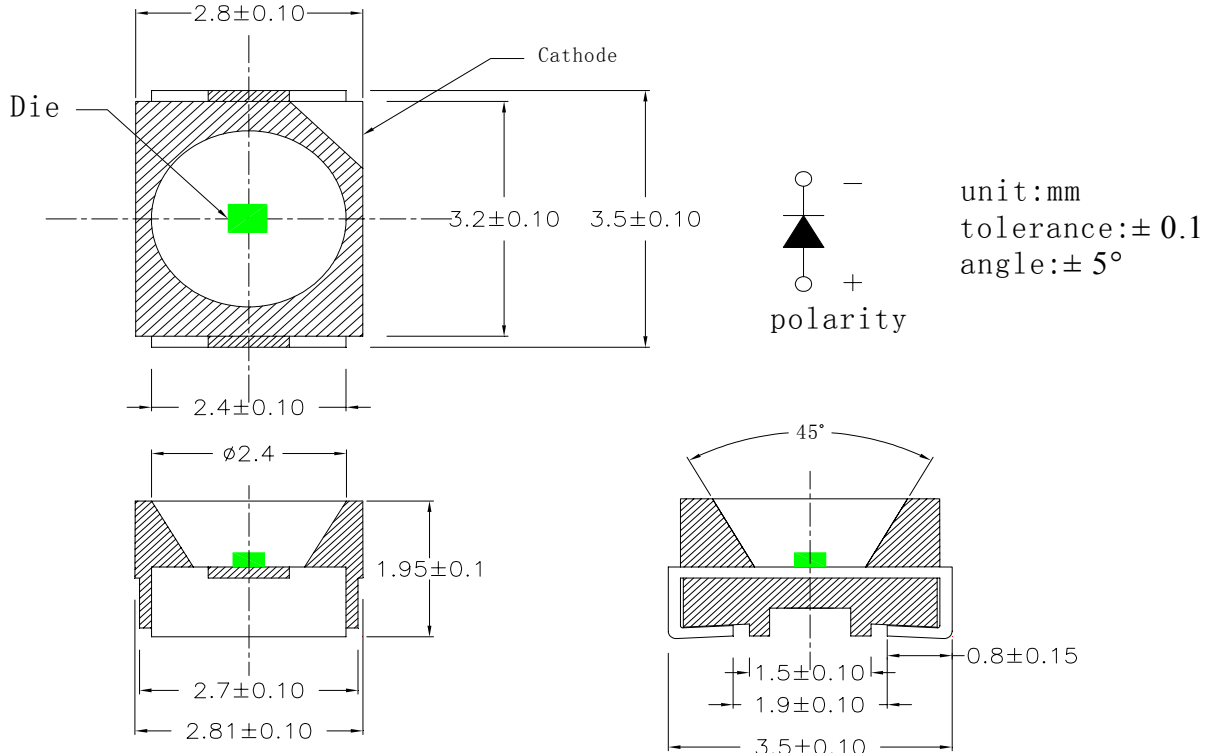
Temp.($^{\circ}\text{C}$)		Time(Sec)	
a	25	T1~T2	60 ± 20
b	130 ± 10	T2~T3	
c	185	T3~T6	
d	250 ± 3	T4~T5	3 ± 2





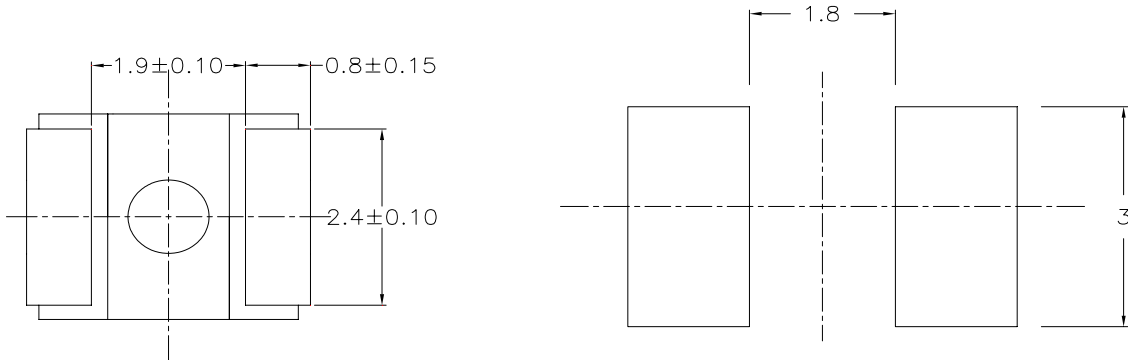
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◆ Package Dimensions of Device (LS-SF67(8)1 Series)



1. Soldering terminal may shift in x, y direction.
2. Polarity referring onto the cathode mark is reversed on the UR/HR/SR

◆ Recommended Soldering Pad Dimensions

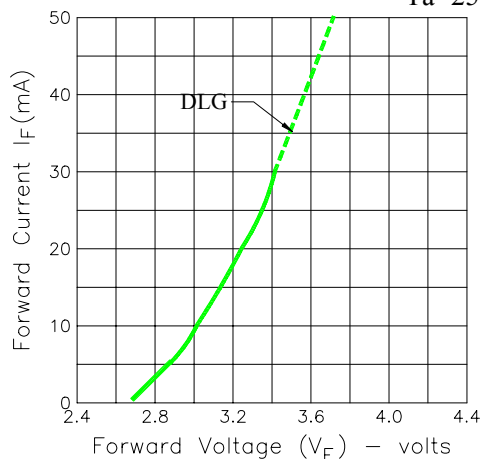


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◆Typical Electro-Optical Characteristic Curves:

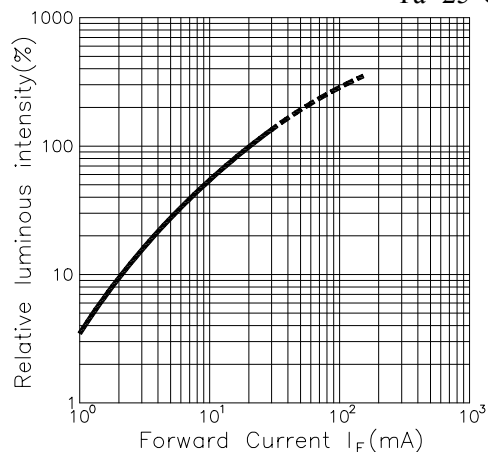
Forward Current Vs. Forward Voltage

Ta=25°C

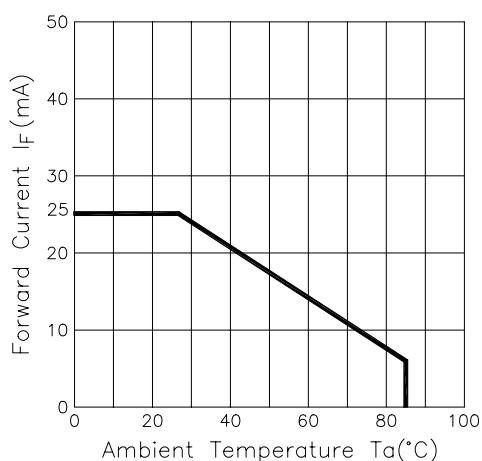


Luminous Intensity Vs. Forward Current

Ta=25°C

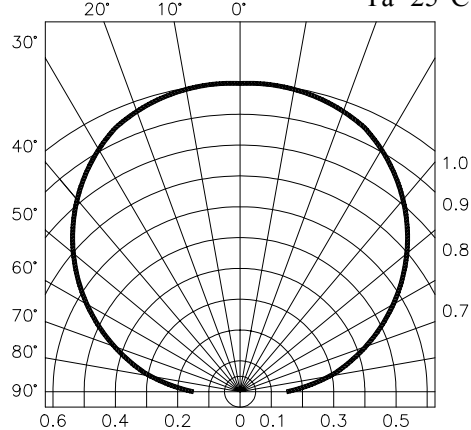


Forward Current Derating Curve

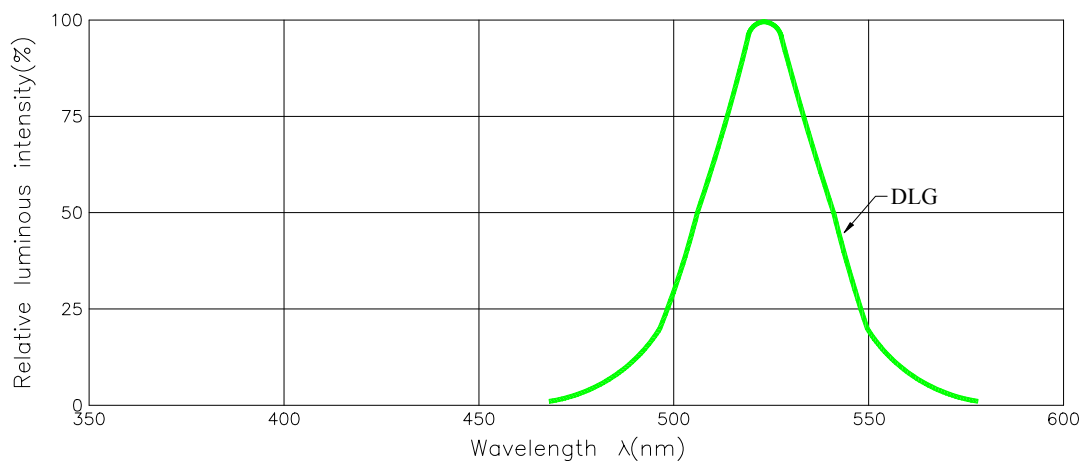


Radiation Diagram

Ta=25°C



Spectrum Distribution

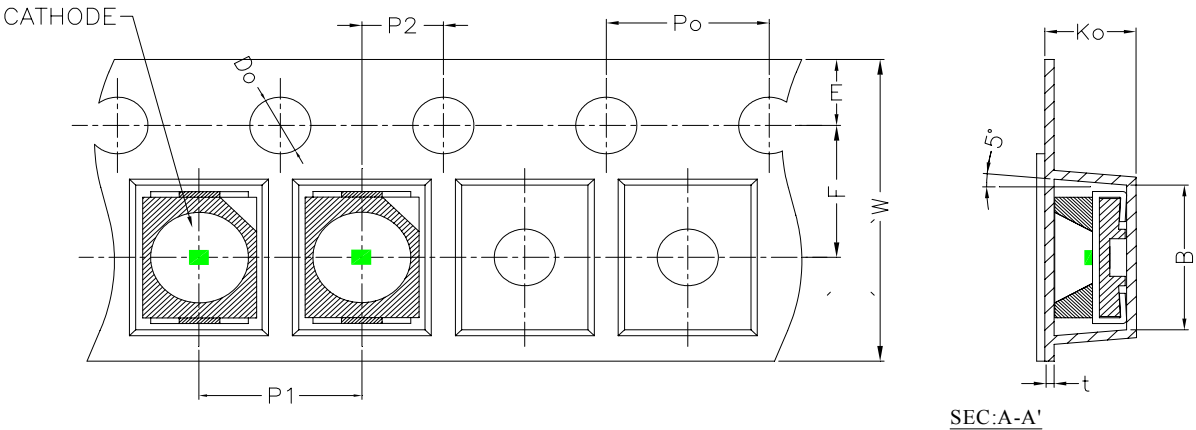




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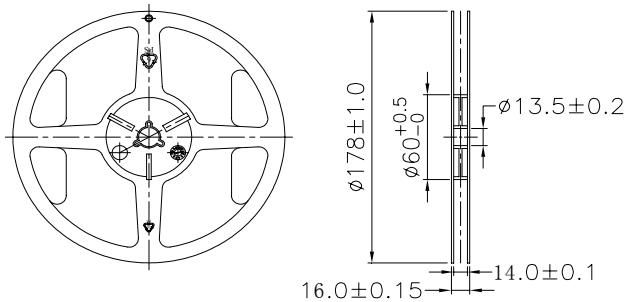
◆ Tape Specification : 2000pcs Per Reel

Packing Size													
Item	W	P1	E	F	D _o	D1	P _o	10P _o	P2	A _o	B _o	K _o	t
Spec.	8.0	4.00	1.75	5.50	1.5	0.5	4.00	40.00	2.00	3.10	3.84	2.24	0.23
Tolerance	±0.20	±0.10	±0.10	±0.05	+0.10 -0.00	±0.05	±0.05	±0.20	±0.05	±0.10	±0.10	±0.10	±0.05



Unit:mm

◆ Package Dimensions of Reel



◆ Label explanation

Product No: LS-XXXXXXXXXX	
Lot No: XXXXXXXXX	
Q'ty: XXXX	PCS
Q.C: XXXXXX	BIN
Date:XXXX.XX.XX	